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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Yoshihiro NAKAJIMA, et al.

Appln. No.: 09/941,744

Confirmation No.: 7388

Filed: August 30, 2001

For: SEMICONDUCTOR DEVICE WITH UNEVEN
METAL PLATE TO IMPROVE ADHESION TO
MOLDING COMPOUND (as amended)

Docket No: Q64096

Allowed: February 27, 2004

Group Art Unit: 2826

Examiner: Pershelle L. GREENE

SUBMISSION OF DRAWINGS

MAIL STOP ISSUE FEE

ATTN: OFFICIAL DRAFTSPERSON

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Submitted herewith please find 11 sheets of drawings in compliance with 37 C.F.R. § 1.84. The Examiner is respectfully requested to acknowledge receipt of these drawings.

The submitted drawings incorporate the proposed drawing correction approved in Paper No. 14. In addition, with regard to Figs. 1A, 2A, 3A, 4A, 5A, 6A, 7A, 9A, and 10A, as indicated on the attached marked-up (in red ink) drawing sheets, the designations of the sectional view lines have been corrected to correspond to the designations as set forth in the specification. No new matter has been added.

Respectfully submitted,

Stan Torgovitsky

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WASHINGTON OFFICE

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CUSTOMER NUMBER

Date: April 15, 2004